

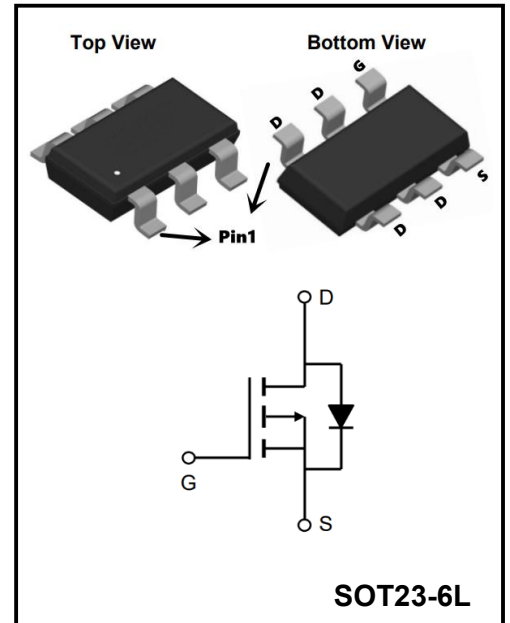
**-20V P-Channel Enhancement Mode MOSFET**

**MAIN CHARACTERISTICS**

<b>I<sub>D</sub></b>	-8.1A
<b>V<sub>DSS</sub></b>	-20V
<b>R<sub>DS(on)-typ(@V<sub>GS</sub>=-4.5V)</sub></b>	< 35mΩ( <b>Type:28mΩ</b> )

**Description**

The YFW 8P02LI uses advanced trench technology to provide excellent R<sub>DS(ON)</sub>, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



**Application**

- Battery protection
- Load switch
- Uninterruptible power supply

**Package Marking and Ordering Information**

Part Number	Package	Marking	Pack
YFW8P02LI	SOT23-6L	YFW 8P02LI	3000PCS/Tape

**Absolute Maximum Ratings (T<sub>c</sub>=25°C unless otherwise noted)**

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V <sub>DS</sub>	-20	V
Gate-Source Voltage	V <sub>GS</sub>	±12	V
Continuous Drain Current, V <sub>GS</sub> @ -4.5V <sup>1</sup>	I <sub>D</sub> @T <sub>A</sub> =25°C	-8.1	A
Continuous Drain Current, V <sub>GS</sub> @ -4.5V <sup>1</sup>	I <sub>D</sub> @T <sub>A</sub> =70°C	-5.9	A
Pulsed Drain Current <sup>2</sup>	I <sub>DM</sub>	-22	A
Total Power Dissipation <sup>3</sup>	P <sub>D</sub> @T <sub>A</sub> =25°C	4.31	W
Total Power Dissipation <sup>3</sup>	P <sub>D</sub> @T <sub>A</sub> =70°C	0.84	W
Storage Temperature Range	T <sub>STG</sub>	-55 to 150	°C
Operating Junction Temperature Range	T <sub>J</sub>	-55 to 150	°C
Thermal Resistance Junction-Ambient <sup>1</sup>	R <sub>θJA</sub>	125	°C/W
Thermal resistance, junction-case	R <sub>θJC</sub>	7.4	°C/W

**Electrical Characteristics ( $T_J=25^{\circ}\text{C}$ , unless otherwise noted)**

Parameter	Conditions	Symbol	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	$BV_{DSS}$	-20	-23	---	V
$BV_{DSS}$ Temperature Coefficient	Reference to $25^{\circ}\text{C}$ , $I_D=-1\text{mA}$	$\Delta BV_{DSS}/\Delta T_J$	---	-0.014	---	$\text{V}/^{\circ}\text{C}$
Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=-4.5V, I_D=-4.9A$	$R_{DS(ON)}$	---	28	35	m $\Omega$
	$V_{GS}=-2.5V, I_D=-3.4A$		---	35	45	
	$V_{GS}=-1.8V, I_D=-2A$		---	50	70	
Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=-250\mu A$	$V_{GS(th)}$	-0.5	-0.65	-1.2	V
$V_{GS(th)}$ Temperature Coefficient		$\Delta V_{GS(th)}$	---	3.95	---	$\text{mV}/^{\circ}\text{C}$
Drain-Source Leakage Current	$V_{DS}=-16V, V_{GS}=0V, T_J=25^{\circ}\text{C}$	$I_{DSS}$	---	---	-1	uA
	$V_{DS}=-16V, V_{GS}=0V, T_J=55^{\circ}\text{C}$		---	---	-5	
Gate-Source Leakage Current	$V_{GS}=\pm 12V, V_{DS}=0V$	$I_{GSS}$	---	---	$\pm 100$	nA
Forward Transconductance	$V_{DS}=-5V, I_D=-3A$	$g_{fs}$	---	12.8	---	S
Total Gate Charge (-4.5V)	$V_{DS}=-15V, V_{GS}=-4.5V, I_D=-3A$	$Q_g$	---	10.2	14.3	nC
Gate-Source Charge		$Q_{gs}$	---	1.89	2.6	
Gate-Drain Charge		$Q_{gd}$	---	3.1	4.3	
Turn-On Delay Time	$V_{DD}=-10V, V_{GS}=-4.5V,$ $R_G=3.3, I_D=-3A$	$T_{d(on)}$	---	5.6	11.2	ns
Rise Time		$T_r$	---	40.8	73	
Turn-Off Delay Time		$T_{d(off)}$	---	33.6	67	
Fall Time		$T_f$	---	18	36	
Input Capacitance	$V_{DS}=-15V, V_{GS}=0V, f=1\text{MHz}$	$C_{iss}$	---	857	1200	pF
Output Capacitance		$C_{oss}$	---	114	160	
Reverse Transfer Capacitance		$C_{rss}$	---	108	151	
Continuous Source Current <sup>1,4</sup>	$V_G=V_D=0V, \text{Force Current}$	$I_S$	---	---	-4.9	A
Pulsed Source Current <sup>2,4</sup>		$I_{SM}$	---	---	-14	A
Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_S=-1A, T_J=25^{\circ}\text{C}$	$V_{SD}$	---	---	-1	V
Reverse Recovery Time	$I_F=-3A, di/dt=100A/\mu s,$ $T_J=25^{\circ}\text{C}$	$t_{rr}$	---	21.8	---	nS
Reverse Recovery Charge		$Q_{rr}$	---	6.9	---	nC

Note :

- 1、The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper. 2、The data tested by pulsed , pulse width  $\Delta 300\mu s$  , duty cycle  $\Delta 2\%$
- 3、The power dissipation is limited by  $150^{\circ}\text{C}$  junction temperature
- 4、The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

Typical Characteristics

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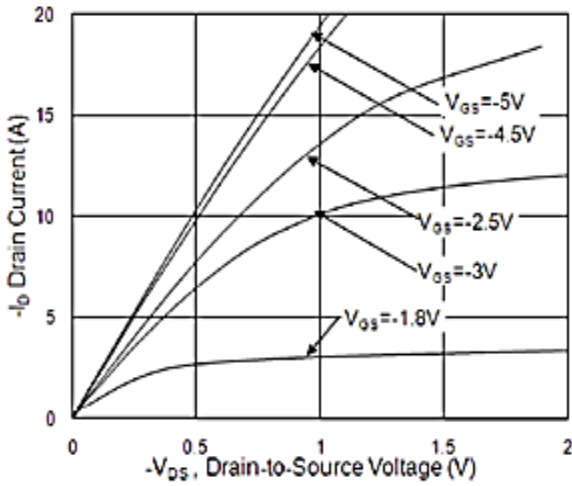


Fig.1 Typical Output Characteristics

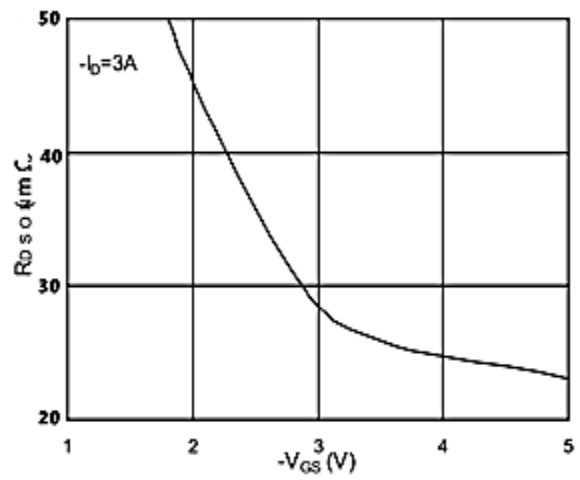


Fig.2 On-Resistance vs. G-S Voltage

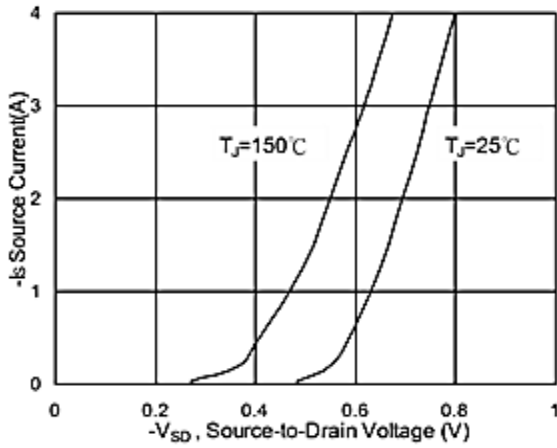


Fig.3 Forward Characteristics of Reverse

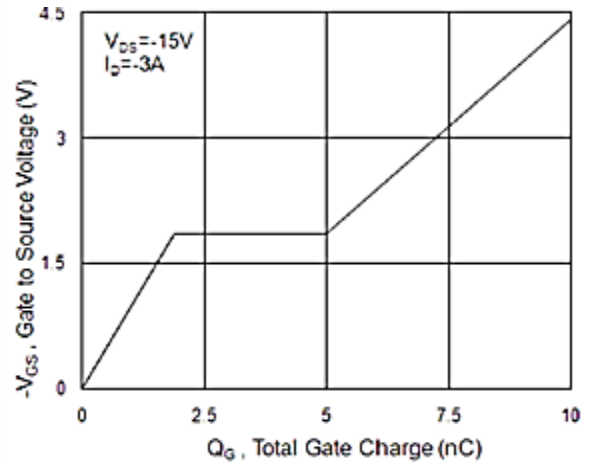


Fig.4 Gate-charge Characteristics

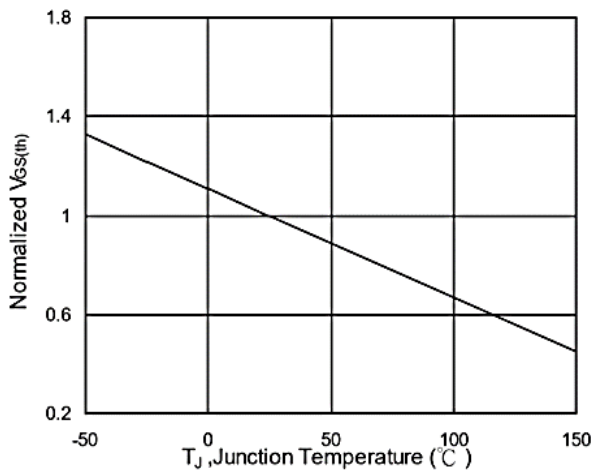


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

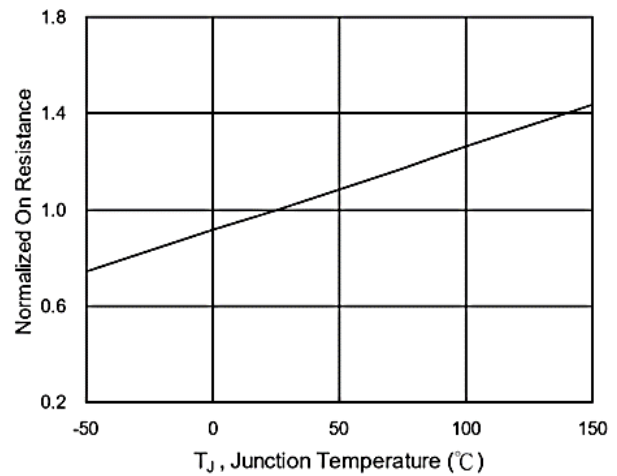


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

Typical Characteristics

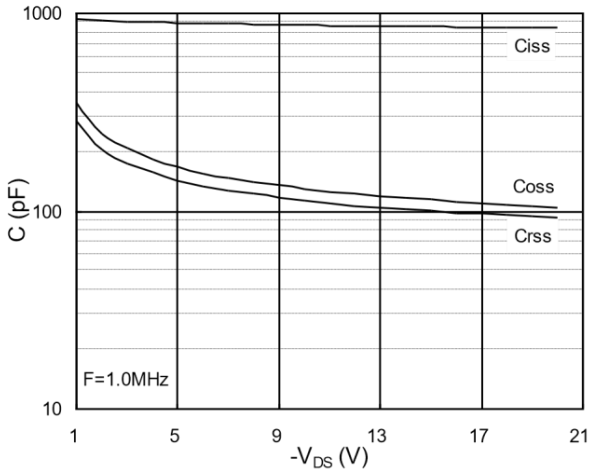


Fig.7 Capacitance

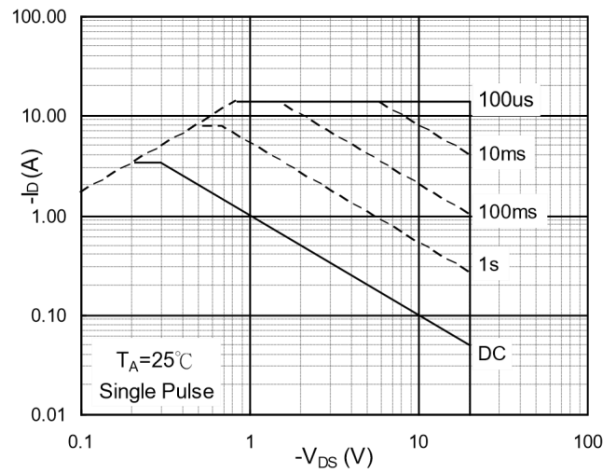


Fig.8 Safe Operating Area

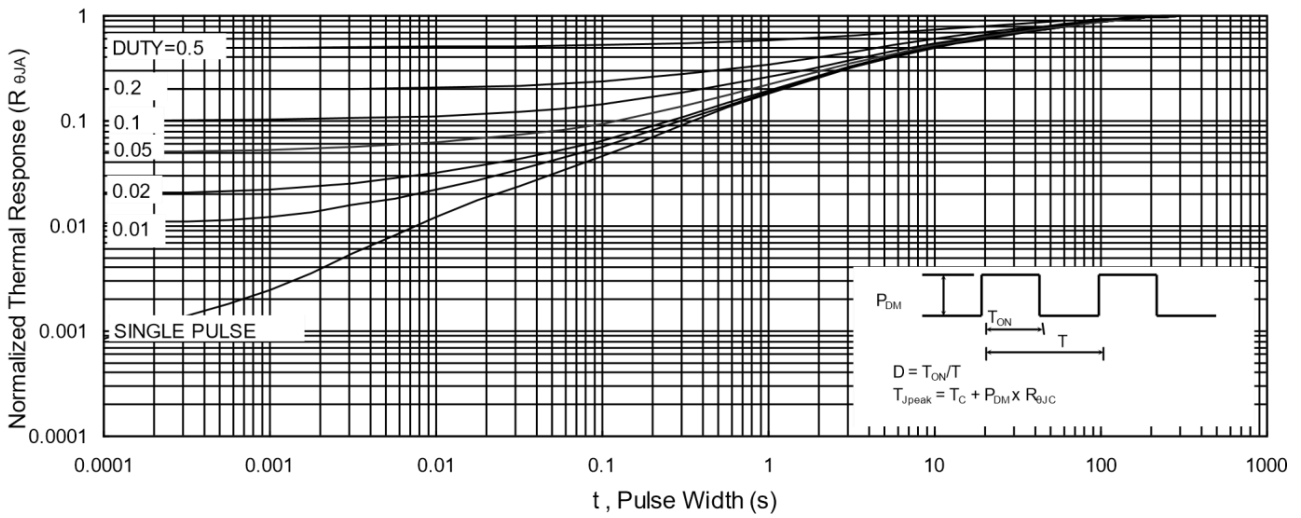


Fig.9 Normalized Maximum Transient Thermal Impedance

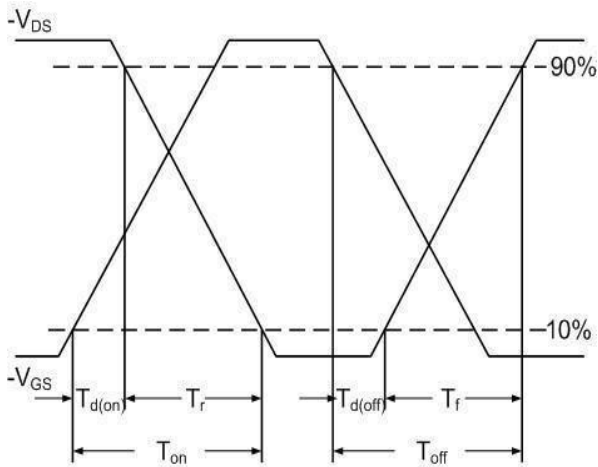


Fig.10 Switching Time Waveform

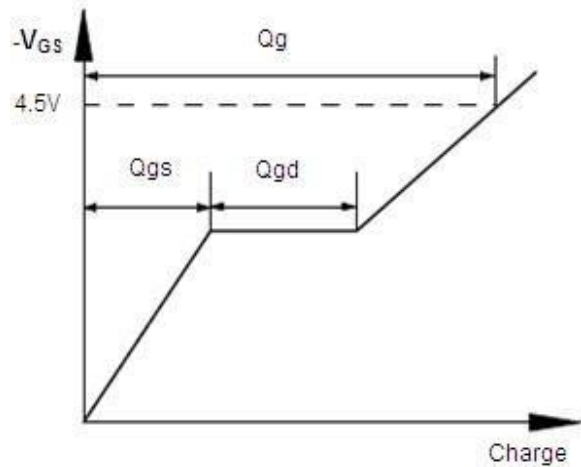
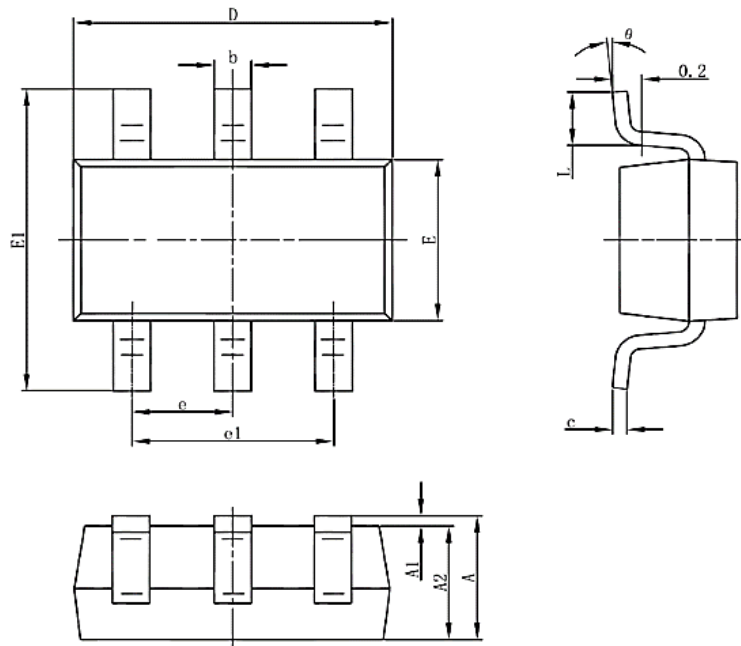


Fig.11 Gate Charge Waveform

Package Outline

SOT23-6



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
C	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950 (BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0	8	0	8